

**Abstract****METHOD FOR PLATING AND PLATING SOLUTION THEREFOR**

5        A solution is described, in particular for electroless deposition of a metal on a polyimide substrate. The solution from which the metal is deposited, comprises a source of metal ions; a reducing agent; an additive to adjust the pH of said bath to a predetermined value; and an aromatic sulfonic acid. The solution is used in a method for electroless deposition of a metal onto a substrate wherein the substrate preferably  
10      comprises polyimide exposed at a surface thereof. The method of the present invention provides a metal layer which shows good adhesion towards the polyimide substrate and which is very smooth and does not need any additional smoothening treatment.

15